NSN 5962-01-299-6398

Memory Microcircuit - Page 1 of 1



View Online at https://aerobasegroup.com/nsn/5962-01-299-6398

view Offilite at https://defobasegroup.com/hsr//5502-01-255-0550
Body Length:
Between 0.540 inches and 0.560 inches
Body Width:
Between 0.442 inches and 0.458 inches
Body Height:
Between 0.054 inches and 0.088 inches
Maximum Power Dissipation Rating:
788.0 milliwatts
Operating Tempurature Range:
-55.0/+125.0 degrees celsius
Storage Tempurature Range:
-65.0/+150.0 degrees celsius
Features Provided:
Electrostatic sensitive and hermetically sealed and w/enable and burn in and programmable and erasable
Inclosure Material:
Ceramic
Inclosure Configuration:
Leadless flat pack
Output Logic Form:
Metal oxide-semiconductor logic
Input Circuit Pattern:
22 input
Terminal Surface Treatment:
Solder
Voltage Rating And Type Per Characteristic:
6.0 volts power source
Time Rating Per Chacteristic:
250.00 nanoseconds propagation delay time, low to high level output and 250.00 nanoseconds propagation delay time, high to low level
output
Memory Device Type:
Rom
Test Data Document:
96906-mil-std-883 standard (includes industry or association standards, individual manufactureer standards, etc.).
Terminal Type And Quantity:
32 leadless
Shelf Life:
N/a
Unit Of Measure:

Demilitarization:

Fiig:

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Yes - demil/mli